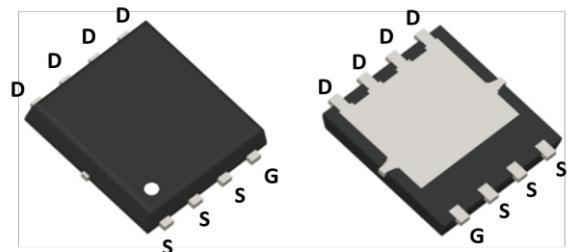


### Product Summary

- V<sub>DS</sub> 40 V
- I<sub>D</sub> 130 A
- R<sub>DS(ON)</sub> (at V<sub>GS</sub> =10V) < 1.8 mohm
- R<sub>DS(ON)</sub> (at V<sub>GS</sub> =4.5V) < 3.0 mohm
- 100% UIS Tested
- 100% ▽ VDSTested

Product Summary			
V <sub>DS</sub>	R <sub>DS(on)</sub> (mΩ) Typ	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ)
40V	1.3@ 10V	130	96.8nC

### DFN5060-8L

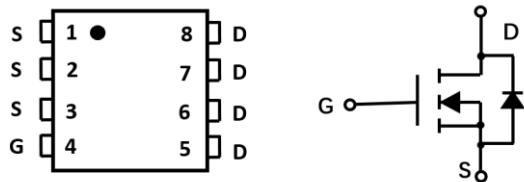


### General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low R<sub>DS(ON)</sub> DS(ON)

### Application

- Motor control
- Synchronous -rectification
- Consumer electronic power supply
- Invertors



### Mechanical Data

- Case:DFN5060-8L Package

Table1 Absolute Maximum Ratings (T<sub>c</sub>=25°C, unless otherwise specified)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	40	V
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current	T <sub>c</sub> =25°C	I <sub>D</sub>	130	A
	T <sub>c</sub> =100°C		82	
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	390	A
Single Pulse Avalanche Energy (Note 2)		E <sub>AS</sub>	200	mJ
Power Dissipation	T <sub>c</sub> =25°C	P <sub>D</sub>	140	W
	T <sub>c</sub> =100°C		56	
Operating Junction and Storage Temperature		T <sub>J/T<sub>SG</sub></sub>	-55~+175	°C

Table 2.Thermal Characteristics

Parameter	Symbol	Limit	Unit
Thermal resistance Junction to Ambient	R <sub>θJA</sub>	62	°C/W
Thermal resistance Junction to Case	R <sub>θJC</sub>	0.89	°C/W

Table 3. Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	40	-	-	V
Drain-Source Leakage Current	I <sub>DS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1	μA
Gate- Source Leakage Current	Forward	V <sub>GS</sub> =20V, V <sub>DS</sub> =0V	-	-	100	nA
	Reverse	V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V	-	-	-100	nA
<b>On Characteristics(Note 4)</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.8	2.5	V
Static Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =55A	-	1.3	1.8	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =55A	-	2.0	3.0	
<b>Dynamic Characteristics(Note 5)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1MHz	-	6587	-	pF
Output Capacitance	C <sub>oss</sub>		-	2537	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	179	-	pF
<b>Switching Characteristics (Note 5)</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =20V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V, R <sub>G</sub> =2.0Ω	-	26.6	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	9.3	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	96	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	39	-	ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DS</sub> =20V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	96.8	-	nC
Gate-Source Charge	Q <sub>GS</sub>		-	14.5	-	nC
Gate-Drain Charge	Q <sub>GD</sub>		-	18.4	-	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	-	1.3	V
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>		-	-	130	A
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> =0V, I <sub>F</sub> =20A dI <sub>F</sub> /dt=100A/μs (Note 1)	-	205	-	ns
Reverse Recovery Charge	Q <sub>RR</sub>		-	557	-	nC

Notes : 1 Repetitive Rating:Pulse width limited by maximum junction temperature

2 L=0.3mH, V<sub>DD</sub>=30V, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C

4 Pulse Test: Pulse width ≤300μs, Duty cycle≤2%

5 Guaranteed by design,not subject to production

### Typical Test Circuit

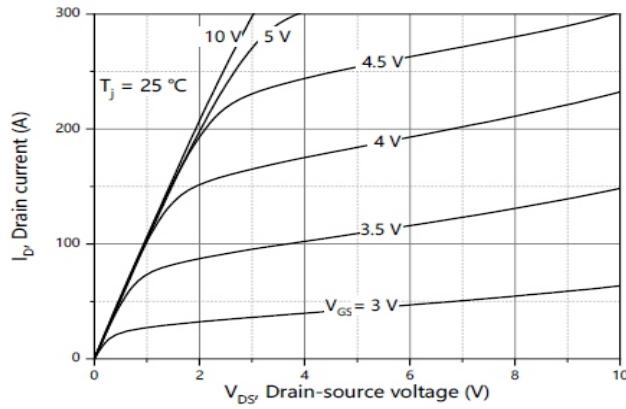


Figure1. Output Characteristics

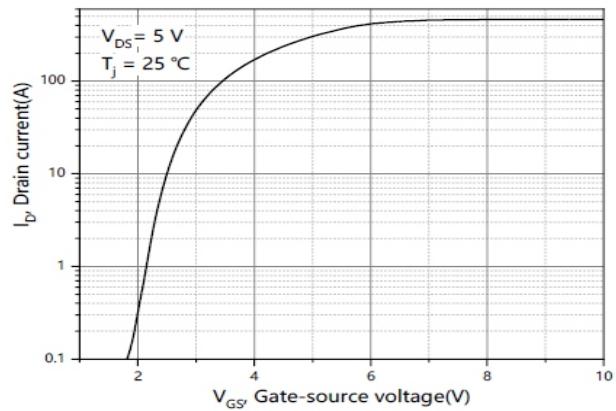


Figure2. Transfer Characteristics

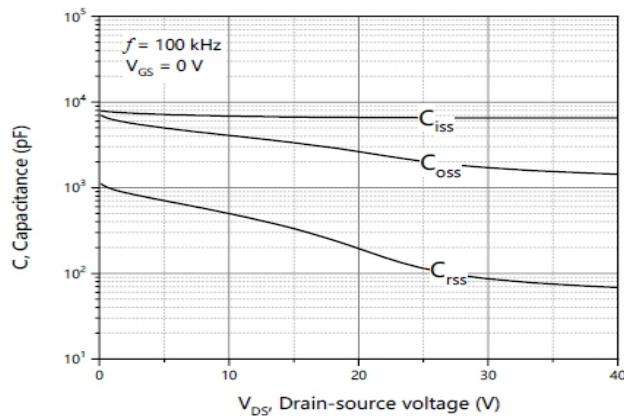


Figure3. Capacitance Characteristics

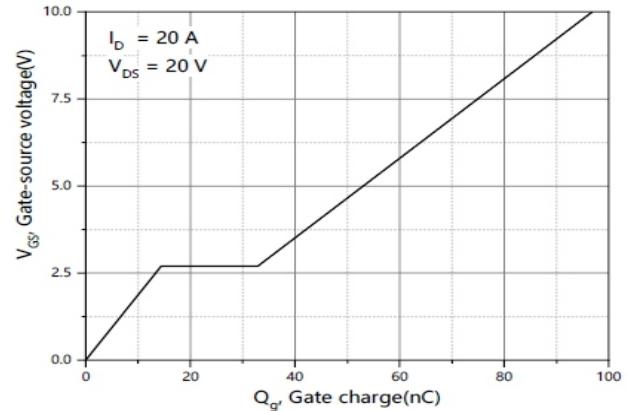


Figure4. Gate Charge

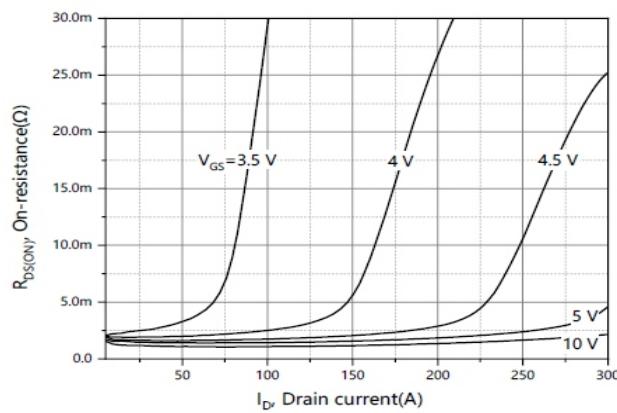


Figure5. Drain -Source on Resistance

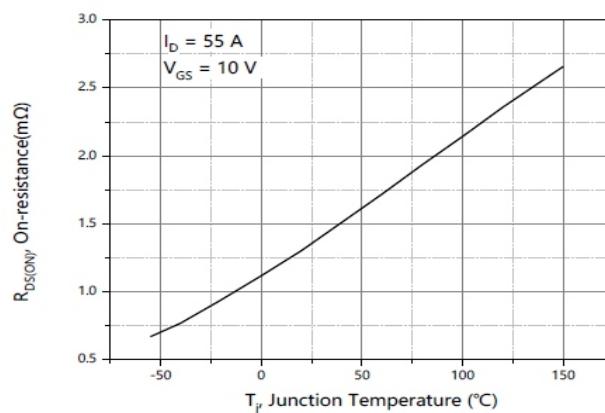


Figure6. Drain -Source on Resistance

## Typical Test Circuit

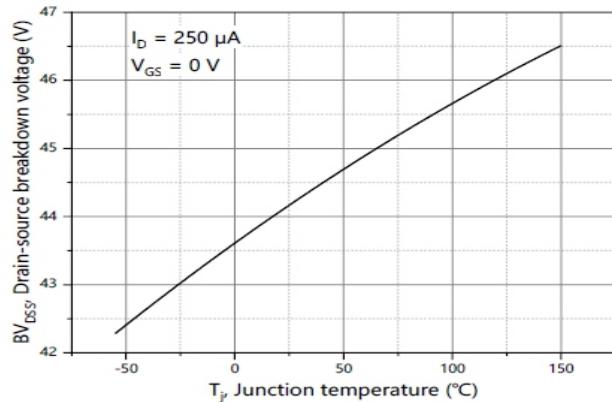


Figure7. Drain-Source Breakdown Voltage

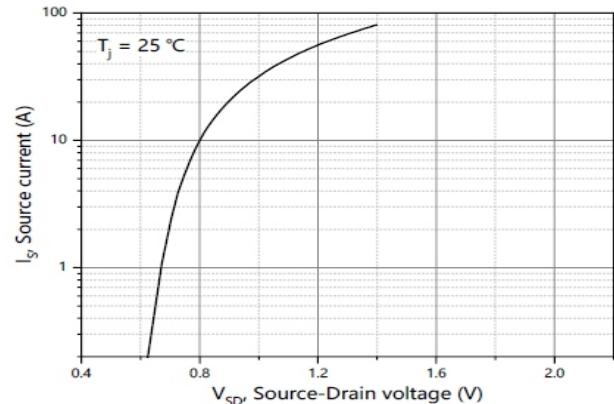


Figure8. Forward Characteristic of Body Diode

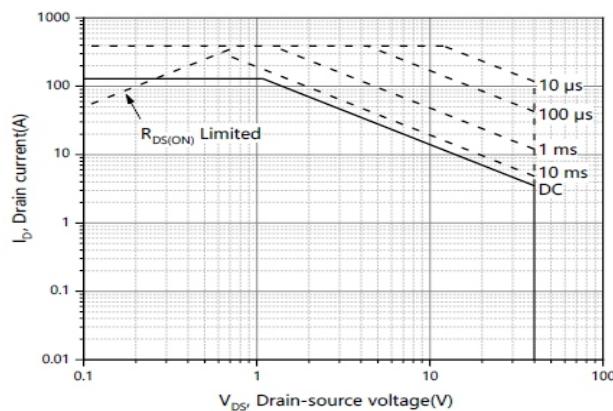


Figure9. Safe Operation Area

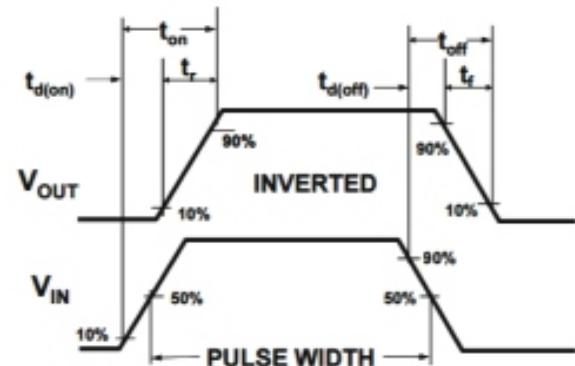
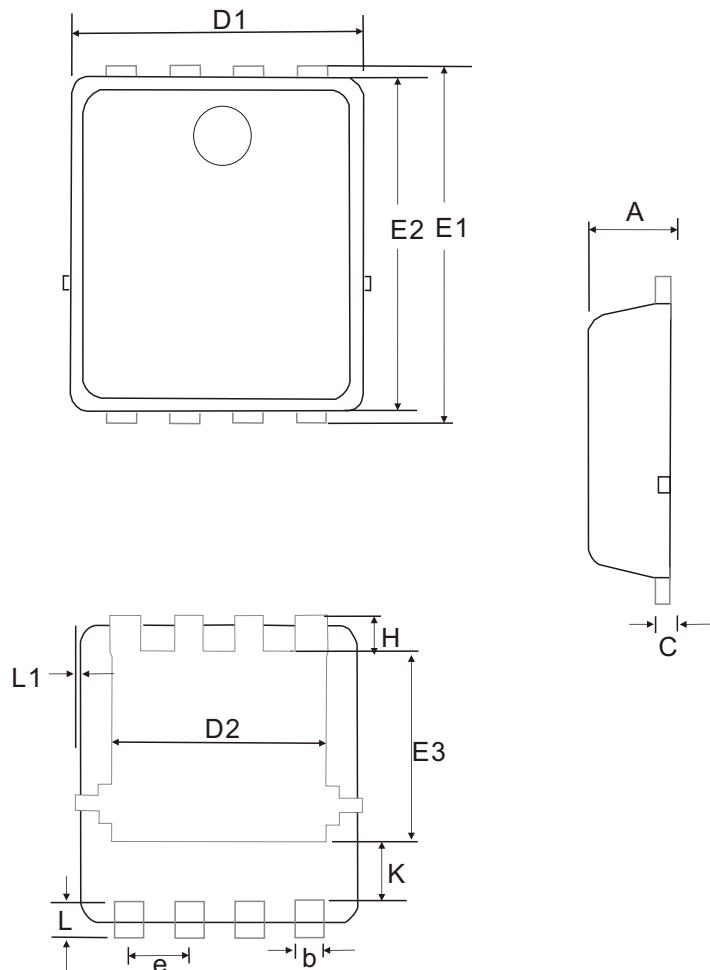


Figure10 . Switching wave

## Dimensions

## DFN5060-8L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions in millimeters	
	Min	Max
A	1.00	1.20
b	0.30	0.50
C	0.154	0.354
D1	5.00	5.40
D2	3.92	4.32
E1	5.95	6.35
E2	5.66	6.06
E3	3.52	3.92
e	1.17	1.37
L	0.00	0.12
L1	0.56	0.76
H	0.40	0.60
K	1.15	1.45

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